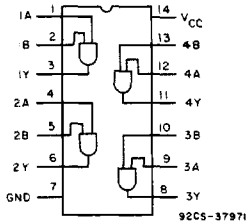


CD54/74HC08 CD54/74HCT08

High-Speed CMOS Logic



**FUNCTIONAL DIAGRAM AND
TERMINAL ASSIGNMENT**

Quad 2-Input AND Gate

Type Features:

- Buffered inputs
- Typical CD54/74HC08 propagation delay=7 ns
@ $V_{CC}=5\text{ V}$, $C_L=15\text{ pF}$, $T_A=25^\circ\text{ C}$

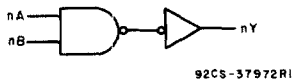
The RCA-CD54/74HC08 and CD54/74HCT08 logic gates utilize silicon-gate CMOS technology to achieve operating speeds similar to LSTTL gates with the low power consumption of standard CMOS integrated circuits. All devices have the ability to drive 10 LSTTL loads. The 54HCT/74HCT logic family is functionally as well as pin compatible with the standard 54LS/74LS logic family.

The CD54HC08 and CD54HCT08 are supplied in 14-lead hermetic dual-in-line ceramic packages (F suffix). The CD74HC08 and CD74HCT08 are supplied in 14-lead dual-in-line plastic packages (E suffix) and in 14-lead dual-in-line surface mount plastic package (M suffix). Both types are also available in chip form (H suffix).

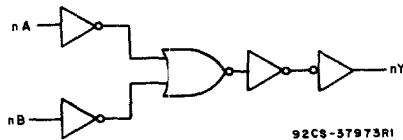
Family Features:

- Fanout (Over Temperature Range):
Standard Outputs - 10 LSTTL Loads
Bus Driver Outputs - 15 LSTTL Loads
- Wide Operating Temperature Range:
CD74HC/HCT: -40 to $+85^\circ\text{ C}$
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- Alternate Source is Philips/Signetics
- CD54HC/CD74HC Types:
2 to 6 V Operation
High Noise Immunity:
 $N_{IL}=30\%$, $N_{IH}=30\%$ of V_{CC} @ $V_{CC}=5\text{ V}$
- CD54HCT/CD74HCT Types:
4.5 to 5.5 V Operation
Direct LSTTL Input Logic Compatibility
 $V_{IL}=0.8\text{ V Max.}$, $V_{IH}=2\text{ V Min.}$
CMOS Input Compatibility
 $I_i \leq 1\text{ }\mu\text{A}$ @ V_{OL} , V_{OH}

LOGIC DIAGRAMS



CD54/74HC08



CD54/74HCT08

TRUTH TABLE

INPUTS		OUTPUTS
nA	nB	nY
L	L	L
L	H	L
H	L	L
H	H	H

CD54/74HC08 CD54/74HCT08

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE, (V_{CC}):	
(Voltages referenced to ground)	-0.5 to +7 V
DC INPUT DIODE CURRENT, I_{IK} (FOR $V_i < -0.5$ V OR $V_i > V_{CC} + 0.5$ V)	± 20 mA
DC OUTPUT DIODE CURRENT, I_{OK} (FOR $V_o < -0.5$ V OR $V_o > V_{CC} + 0.5$ V)	± 20 mA
DC DRAIN CURRENT, PER OUTPUT (I_o) (FOR -0.5 V $< V_o < V_{CC} + 0.5$ V)	± 25 mA
DC V_{CC} OR GROUND CURRENT (I_{CC}):	± 50 mA
POWER DISSIPATION PER PACKAGE (P_D):	
For $T_A = -40$ to $+60^\circ$ C (PACKAGE TYPE E)	500 mW
For $T_A = +60$ to $+85^\circ$ C (PACKAGE TYPE E)	Derate Linearly at 8 mW/ $^\circ$ C to 300 mW
For $T_A = -55$ to $+100^\circ$ C (PACKAGE TYPE F, H)	500 mW
For $T_A = +100$ to $+125^\circ$ C (PACKAGE TYPE F, H)	Derate Linearly at 8 mW/ $^\circ$ C to 300 mW
For $T_A = -40$ to $+70^\circ$ C (PACKAGE TYPE M)	400 mW
For $T_A = +70$ to $+125^\circ$ C (PACKAGE TYPE M)	Derate Linearly at 6 mW/ $^\circ$ C to 70 mW
OPERATING-TEMPERATURE RANGE (T_A):	
PACKAGE TYPE F, H	-55 to $+125^\circ$ C
PACKAGE TYPE E, M	-40 to $+85^\circ$ C
STORAGE TEMPERATURE (T_{STG})	-65 to $+150^\circ$ C
LEAD TEMPERATURE (DURING SOLDERING):	
At distance $1/16 \pm 1/32$ in. (1.59 ± 0.79 mm) from case for 10 s max.	$+265^\circ$ C
Unit inserted into a PC Board (min. thickness $1/16$ in., 1.59 mm) with solder contacting lead tips only	$+300^\circ$ C

RECOMMENDED OPERATING CONDITIONS:

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS		UNITS
	MIN.	MAX.	
Supply-Voltage Range (For T_A =Full Package-Temperature Range) V_{CC} .* CD54/74HC Types CD54/74HCT Types	2 4.5	6 5.5	V
DC Input or Output Voltage V_i, V_o	0	V_{CC}	V
Operating Temperature T_A : CD74 Types CD54 Types	-40 -55	+85 +125	$^\circ$ C
Input Rise and Fall Times t_r, t_f at 2 V at 4.5 V at 6 V	0 0 0	1000 500 400	ns

*Unless otherwise specified, all voltages are referenced to Ground.

CD54/74HC08 CD54/74HCT08

STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CD74HC08/CD54HC08										CD74HCT08/CD54HCT08										UNITS			
	TEST CONDITIONS			74HC/54HC TYPES			74HC TYPES			54HC TYPES			TEST CONDITIONS		74HCT/54HCT TYPES			74HCT TYPES				54HCT TYPES		
	V _I V	I _O mA	V _{CC} V	+25°C			-40/ +85°C			-55/ +125°C			V _I V	V _{CC} V	+25°C			-40/ +85°C				-55/ +125°C		
				Min	Typ	Max	Min	Max	Min	Max	Min	Max			Min	Typ	Max	Min	Max	Min		Max		
High-Level Input Voltage V _{IH}			2	1.5	—	—	1.5	—	1.5	—	—	4.5	to	2	—	—	2	—	2	—	—	V		
			4.5	3.15	—	—	3.15	—	3.15	—	—	5.5												
			6	4.2	—	—	4.2	—	4.2	—	—													
Low-Level Input Voltage V _{IL}			2	—	—	0.5	—	0.5	—	0.5	—	4.5				0.8	—	0.8	—	0.8	—	V		
			4.5	—	—	1.35	—	1.35	—	1.35	—	to												
			6	—	—	1.8	—	1.8	—	1.8	—	5.5												
High-Level Output Voltage V _{OH} or CMOS Loads	V _{IL}	-0.02	2	1.9	—	—	1.9	—	1.9	—	V _{IL}	4.5	4.4	—	—	4.4	—	4.4	—	4.4	—	V		
	V _{IH}		4.5	4.4	—	—	4.4	—	4.4	—	4.4												—	
	V _{IH}		6	5.9	—	—	5.9	—	5.9	—	5.9												—	
TTL Loads	V _{IL}										V _{IL}													
	or	-4	4.5	3.98	—	—	3.84	—	3.7	—	or	4.5	3.98	—	—	3.84	—	3.7	—	—	V			
	V _{IH}	-5.2	6	5.48	—	—	5.34	—	5.2	—	V _{IH}													
Low-Level Output Voltage V _{OL} or CMOS Loads	V _{IL}	0.02	2	—	—	0.1	—	0.1	—	0.1	V _{IL}	4.5	—	—	0.1	—	0.1	—	0.1	—	0.1	V		
	or		4.5	—	—	0.1	—	0.1	—	0.1	—													
	V _{IH}		6	—	—	0.1	—	0.1	—	0.1	—													
TTL Loads	V _{IL}										V _{IL}													
	or	4	4.5	—	—	0.26	—	0.33	—	0.4	or	4.5	—	—	0.26	—	0.33	—	0.4	—	V			
	V _{IH}	5.2	6	—	—	0.26	—	0.33	—	0.4	V _{IH}													
Input Leakage Current I _I	V _{CC} or Gnd		6	—	—	±0.1	—	±1	—	±1	Any Voltage Between V _{CC} & Gnd	5.5	—	—	±0.1	—	±1	—	±1	—	±1	μA		
Quiescent Device Current I _{CC}	V _{CC} or Gnd	0	6	—	—	2	—	20	—	40	V _{CC} or & Gnd	5.5	—	—	2	—	20	—	40	—	40	μA		
Additional Quiescent Device Current per input pin: 1 unit load ΔI _{CC} *											4.5 V _{CC} -2.1 5.5	to	—	100	360	—	450	—	490	—	490	μA		

*For dual-supply systems theoretical worst case (V_I = 2.4 V, V_{CC} = 5.5 V) specification is 1.8 mA.

HCT Input Loading Table

Input	Unit Loads*
All	0.6

*Unit Load is ΔI_{CC} limit specified in Static Characteristic Chart, e.g., 360 μA max. @ 25°C.

CD54/74HC08 CD54/74HCT08

SWITCHING CHARACTERISTICS (V_{CC} = 5 V, T_A = 25° C, Input t_r = 6 ns)

CHARACTERISTIC	SYMBOL	TYPICAL		UNITS
		HC	HCT	
Propagation Delay, Data Input to Output Y (Fig. 1) (C _L =15 pF)	t _{PLH} t _{PHL}	7	10	ns
Power Dissipation Capacitance*	C _{PD}	37	51	pF

*C_{PD} is used to determine the dynamic power consumption, per gate.

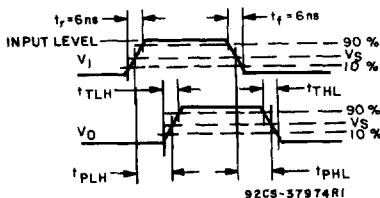
PD = V_{CC}² f_i (C_{PD} + C_L) where f_i = input frequency

C_L = output load capacitance

V_{CC} = supply voltage

SWITCHING CHARACTERISTICS (C_L = 50 pF, Input t_r = 6 ns)

CHARACTERISTIC	SYMBOL	V _{CC}	25° C				-40° C to +85° C				-55° C to +125° C				UNITS
			HC		HCT		74HC		74HCT		54HC		54HCT		
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
Propagation Delay, Input to Output (Fig. 1)	t _{PLH}	2		90		—		115		—		135		—	ns
	t _{PHL}	4.5		18		25		23		31		27		38	
		6		15		—		20		—		23		—	
Transition Times (Fig. 1)	t _{TLH}	2		75		—		95		—		110		—	ns
	t _{THL}	4.5		15		15		19		19		22		22	
		6		13		—		16		—		19		—	
Input Capacitance	C _i			10		10		10		10		10		10	pF



	54/74HC	54/74HCT
Input Level	V _{CC}	3 V
Switching Voltage, V _s	50% V _{CC}	1.3 V

Fig. 1 - Transition times and propagation delay times.